

ETCHING LIQUID FOR POLYIMIDE RESIN AND ETCHING METHOD

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Abstract

PURPOSE: To accurately etch at a sufficiently high rate a polyimide resin obtained from biphenyltetracarboxylic dianhydride and a diamine through polycondensation.
CONSTITUTION: A polyimide resin is etched at 60-90 deg.C with an etchant comprising 20-70vol.% aqueous sodium hydroxide solution (40wt.%), 2-20vol.% ethylenediamine, 10-30vol.% hydrazine monohydrate, 2-10vol.% dimethylamine solution (20wt.%), and 2-10vol.% N,N-dimethylformamide.

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